

高电流、同步降压功率级

 查询样品: **UCD74120**

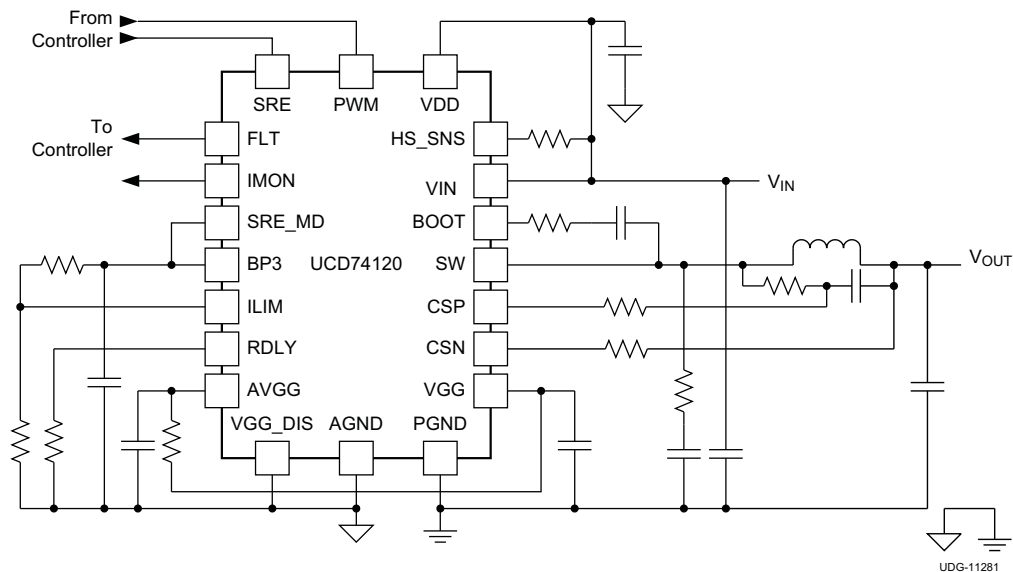
特性

- 集成同步降压驱动器和 **NexFET™** 功率金属氧化物半导体场效应晶体管 (**MOSFET**) 技术用于实现高功率密度和高效率
- 用于数字信号处理器 (**DSP**) 和特定用途集成电路 (**ASIC**) 的 **25A** 输出电流能力
- 输入电压范围 **4.7V** 至 **14V**
- 工作开关频率高达 **2MHz**
- 内置高侧电流保护
- 针对过流保护和输出电流监视的直流电阻 (**DCR**) 电流感测
- 与负载电流监视器输出成比例的电压
- 用于功率级关断的三态脉宽调制 (**PWM**) 输入
- 欠压闭锁 (**UVLO**) 管家电路
- 集成热关断
- **40** 引脚, **5mm x 7mm**, 塑料四方扁平无引线 (**PQFN**) 封装 **PowerStack™** 封装

应用范围

- 数字或模拟负载点 (**POL**) 电源模块
- 针对电信和网络应用的高功率密度 **DC-DC** 转换器

应用图



说明

UCD74120 是一款多芯片模块, 此模块在耐热增强型紧凑, 5mm x 7mm, QFN 封装内集成了一个驱动器器件和两个 NexFET 功率 MOSFET。25A 输出电流能力使得此器件适合为 DSP 和 ASIC 供电。此器件被设计成为数字或模拟 PWM 控制器提供补充。驱动器器件的 PWM 输入是三态兼容的。两个驱动器电路可在同步降压电路中为高侧 N 通道 FET 开关和低侧 N 通道 FET 同步整流器提供高充电及放电电流。

输出电流由一个用于处理外部电流感测元件上电压的精密电流感测放大器进行测量并监视。IMON 引脚上的 PWM 控制器能够使用这个被放大的信号。板载比较器监视高侧开关上的电压以及外部电流感测元件上的电压以保护功率级不受意外高电流负载的影响。针对高侧比较器的消隐延迟由一个单电阻器设定以防止错误报告与开关边沿噪声同时发生。如果发生高侧故障或过流故障, 高侧 FET 关闭并且故障标志 (FLT) 被置为有效以警告 PWM 控制器。



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NexFET, PowerStack are trademarks of Texas Instruments.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION⁽¹⁾

TEMPERATURE RANGE	PINS	PACKAGE	ORDERING NUMBER
–40°C to 125°C	40	RVF	UCD74120RVF

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		VALUE		UNIT
		MIN	MAX	
Voltage range	VDD, VIN	–0.3	16	V
	SW DC	–1	16	V
	SW Pulse < 400 ns, E = 20 μJ	–2	20	V
	SW Pulse < 64 ns	–5	22	V
	SW Pulse < 40 ns	–7	25	V
	VGG, AVGG (Externally supplied)	–0.3	7	V
	BOOT DC	–0.3	23	V
	BOOT Pulse (SW at 20 V < 400 ns)	–0.3	27	V
	BOOT Pulse (SW at 22 V < 64 ns)	–0.3	29	V
	BOOT Pulse (SW at 25 V < 40 ns)	–0.3	32	V
	ILIM, VGG_DIS, IMON, FLT	–0.3	3.6	V
	CSP, CSN, RDLY, PWM, SRE, SRE_MD	–0.3	5.6	V
	HS_SNS	–0.3	16	V
Temperature	T _J	–40	150	°C
	T _{stg}	–55	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those included under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods of time may affect device reliability.

THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		UCD74120	UNITS
		PQFN (RVF) 40-PIN	
θ _{JA}	Junction-to-ambient thermal resistance	28.9	°C/W
θ _{JCtop}	Junction-to-case (top) thermal resistance	15.4	
ψ _{JT}	Junction-to-top characterization parameter	0.2	
ψ _{JB}	Junction-to-board characterization parameter	5.1	
θ _{JCbot}	Junction-to-case (bottom) thermal resistance	0.8	

- (1) 有关传统和新的热 度量的更多信息，请参阅 IC 封装热度量应用报告， [SPRA953](http://www.ti.com)。

RECOMMENDED OPERATING CONDITIONS

	MIN	TYP	MAX	UNIT
VDD, VIN	4.7		14	V
VGG, AVGG Externally supplied gate drive voltage	4.6		6.5	V
T _J Operating junction temperature	-40		125	°C

ELECTROSTATIC DISCHARGE (ESD) PROTECTION

	MIN	TYP	MAX	UNIT
Human body model (HBM)		1.5		kV
Charge device model (CDM)		500		V

ELECTRICAL CHARACTERISTICS
 $T_J = -40^{\circ}\text{C}$ to 125°C , V_{VDD} , $V_{VIN} = 12\text{ V}$, all parameters at zero power dissipation (unless otherwise noted)

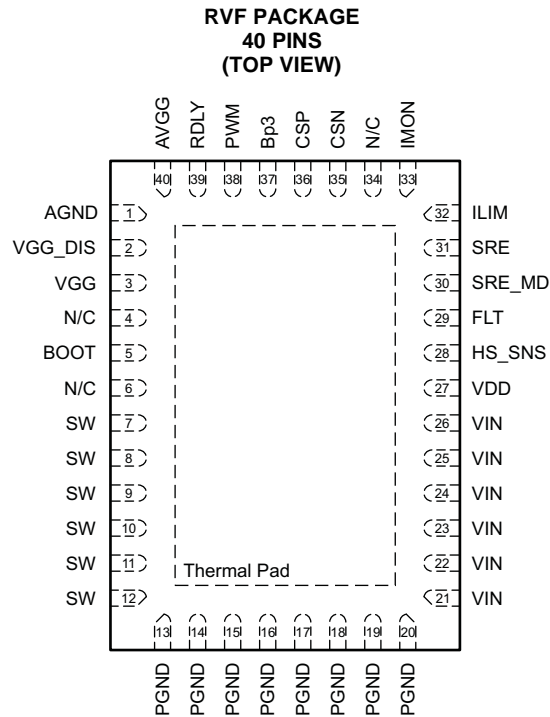
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
INPUT SUPPLY						
V_{VIN}	Input supply voltage range		4.7		14	V
V_{VDD}						
I_{VDD}	Supply current	Not switching, PWM = LOW		8	10	mA
GATE DRIVE UNDER-VOLTAGE LOCKOUT						
V_{GG-ON}	UVLO on voltage			4.4	4.6	V
V_{GG-OFF}	UVLO off voltage		4.1	4.3		V
V_{GG-HYS}	UVLO hysteresis voltage			80		mV
VGG SUPPLY GENERATOR						
V_{GG}	Output voltage	$V_{VIN} = 12\text{ V}$, $I_{GG} = 50\text{ mA}$	5.3	6.0	6.8	V
V_{DO}	Dropout voltage, $V_{VDD} - V_{GG}$	$V_{VIN} = 4.7\text{ V}$, $I_{GG} = 50\text{ mA}$			350	mV
BP3 REGULATOR						
V_{BP3}	Output voltage	$V_{VIN} = 12\text{ V}$, $I_{BP3} = 2\text{ mA}$	3.0	3.2	3.3	V
DIGITAL INPUT SIGNALS (PWM, SRE)						
V_{IH-PWM}	Positive-going input threshold voltage			1.8	2.1	V
V_{IL-PWM}	Negative-going input threshold voltage		0.8	0.9		V
PWM	Input voltage hysteresis, ($V_{IH} - V_{IL}$)			0.9		V
V_{IH-SRE}	Positive-going input threshold voltage			1.5	1.7	V
V_{IL-SRE}	Negative-going input threshold voltage		0.9	1.0		V
SRE	Input voltage hysteresis, ($V_{IH} - V_{IL}$)			0.45		V
I_{PWM}	Input current	$V_{PWM} = 5\text{ V}$		140		μA
		$V_{PWM} = 3.3\text{ V}$		70		
		$V_{PWM} = 0\text{ V}$		-63		
I_{SRE}	Input current	$V_{SRE} = 5\text{ V}$		190		μA
		$V_{SRE} = 3.3\text{ V}$		12		
		$V_{SRE} = 0\text{ V}$		-330		
$t_{HLD-R}^{(1)}$	tri-state hold-off time	V_{PWM} transition from 0 V to 1.65 V, time until low-side drive falls to 0 V	450	600	750	ns
OUTPUT CURRENT LIMIT (ILIM)						
$R_{ILIM-IN}^{(1)}$	ILIM input impedance			250		k Ω
V_{ILIM}	ILIM set point range		0.5		3	V
V_{FLT-HI}	FLT output high level	$I_{LOAD} = -2\text{ mA}$	2.7	3.3		V
V_{FLT-LO}	FLT output low level	$I_{LOAD} = 2\text{ mA}$		0.1	0.6	V
$t_{FAULT-FLT}^{(1)}$	Fault detection time. Delay until FLT asserted	$V_{ILIM} = 1.5\text{ V}$, ($V_{CSP} - V_{CSN}$) = 20 mV, $V_{CSN} = 1.8\text{ V}$		350	475	ns
$t_{DLY}^{(1)}$	Propagation delay from PWM to reset FLT	PWM falling to FLT falling after a current limit event is cleared. PWM pulse width $\geq 100\text{ ns}$		85	200	ns
CURRENT SENSE BLANKING (RDLY, HS_SNS)						
I_{RDLY}	RDLY source current	8.06 k Ω resistor from RDLY to AGND		90		μA
$R_{RDLY}^{(1)}$	RDLY resistance range		5.00	8.06	25.00	k Ω
t_{BLANK}	HS_SNS blanking time	$R_{RDLY} = 8.06\text{ k}\Omega$. From SW rising to HS fault comparator enabled.	110	125	140	ns
I_{OCH}	Overcurrent threshold for high-side FET	$T_J = 25^{\circ}\text{C}$, ($V_{BOOT} - V_{SW}$) = 5.5V		50		A

(1) Ensured by design. Not production tested.

ELECTRICAL CHARACTERISTICS (continued)
 $T_J = -40^{\circ}\text{C}$ to 125°C , V_{DD} , $V_{IN} = 12\text{ V}$, all parameters at zero power dissipation (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
CURRENT SENSE AMPLIFIER (IMON, CSP, CSN)						
V_{IMON}	IMON voltage at no load	$CSP = CSN = 1.8\text{ V}$	0.46	0.50	0.54	V
$R_{CS-IN}^{(2)}$	Input impedance	Differential, $(V_{CSP} - V_{CSN})$		100		k Ω
G_{CS}	Closed loop DC gain	$(V_{CSP} - V_{CSN}) = 10\text{ mV}$, $0.5\text{ V} \leq V_{CSN} \leq 3.3\text{ V}$	48	50.2	52.4	V/V
		Gain with 2.49 k Ω resistors in series with CSP, CSN	45.0	47.0	49.2	
$V_{CM}^{(2)}$	Input common mode voltage range	V_{CM} maximum is limited to $(V_{VGG} - 1.2\text{ V})$	-0.3		5.3	V
$V_{IMON(min)}$	Minimum IMON voltage	$V_{CSP} = 1.2\text{ V}$; $V_{CSN} = 1.3\text{ V}$, $I_{IMON} = -250\text{ }\mu\text{A}$		0.1	0.15	V
$V_{IMON(max)}$	Maximum IMON voltage	$V_{CSP} = 1.3\text{ V}$; $V_{CSN} = 1.2\text{ V}$, $I_{IMON} = 500\text{ }\mu\text{A}$	3.0	3.2	3.3	V
$SR^{(2)}$	Sampling rate			5		Msp/s
OUTPUT STAGE						
R_{HI}	High side device resistance	$T_J = 25^{\circ}\text{C}$, $V_{BOOT} - V_{SW} = 5.5\text{ V}$		4.5	6.5	m Ω
R_{LO}	Low side device resistance	$T_J = 25^{\circ}\text{C}$		1.9	2.7	
BOOTSTRAP DIODE						
V_F	Forward voltage	Forward bias current 20 mA		0.4		V
THERMAL SHUTDOWN						
$T_{TSD-R}^{(2)}$	Rising threshold		155	165	175	$^{\circ}\text{C}$
$T_{TSD-F}^{(2)}$	Falling threshold		135	145	155	$^{\circ}\text{C}$
$T_{TSD-HYS}^{(2)}$	Hysteresis			20		$^{\circ}\text{C}$

(2) Ensured by design. Not production tested.

DEVICE INFORMATION


The thermal pad is also an electrical ground connection.

PIN FUNCTIONS

PIN		I/O	DESCRIPTION
NAME	NO.		
AGND	1		Analog ground return for all circuits except the low-side gate driver. The analog ground and power ground should be connected together at one point, near the AGND pin.
AVGG	40	I/O	Voltage supply to internal control circuitry. Connect a low ESR bypass ceramic capacitor of 100 nF or greater from this pin to AGND. Also a resistor of 1Ω to 2 Ω must be connected between VGG and this pin.
BOOT	5	I/O	Floating bootstrap supply for high side driver. Connect the bootstrap capacitor between this pin and the SW node. The bootstrap capacitor provides the charge to turn on the high-side FET. A low ESR ceramic capacitor of 220 nF or greater from this pin to SW must be connected.
BP3	37	O	Output bypass for the internal 3.3V regulator. Connect a low ESR bypass ceramic capacitor of 1 μF or greater from this pin to AGND.
CSN	35	I	Inverting input of the output current sense amplifier and current limit comparator.
CSP	36	I	Non-inverting input of the output current sense amplifier and current limit comparator.
FLT	29	O	Fault Flag. The FLT signal is a 3.3V digital output which is asserted high when an overcurrent, over-temperature, or UVLO fault is detected. After an overcurrent event is detected, the flag is reset low on the falling edge of the next PWM pin, provided the overcurrent condition is no longer detected during the on-time of the PWM signal. For UVLO and over-temperature faults, the flag is reset when the fault condition is no longer present.
HS_SNS	28	I	A 2-kΩ resistor must be connected from this pin directly to the drain of the high-side FET.
ILIM	32	I	Output current limit threshold set pin. The voltage on this pin sets the fault threshold voltage on the IMON pin. The nominal threshold voltage range is 0.5 V to 3.0 V. When V(IMON) exceeds V(ILIM), the FLT pin is asserted and the high-side gate pulse is truncated.
IMON	33	O	Current sense linear amplifier output. The output voltage level on this pin represents the average output current. $V(IMON) = 0.5 V + 50.2(V(CSP) - V(CSN))$.

PIN FUNCTIONS (continued)

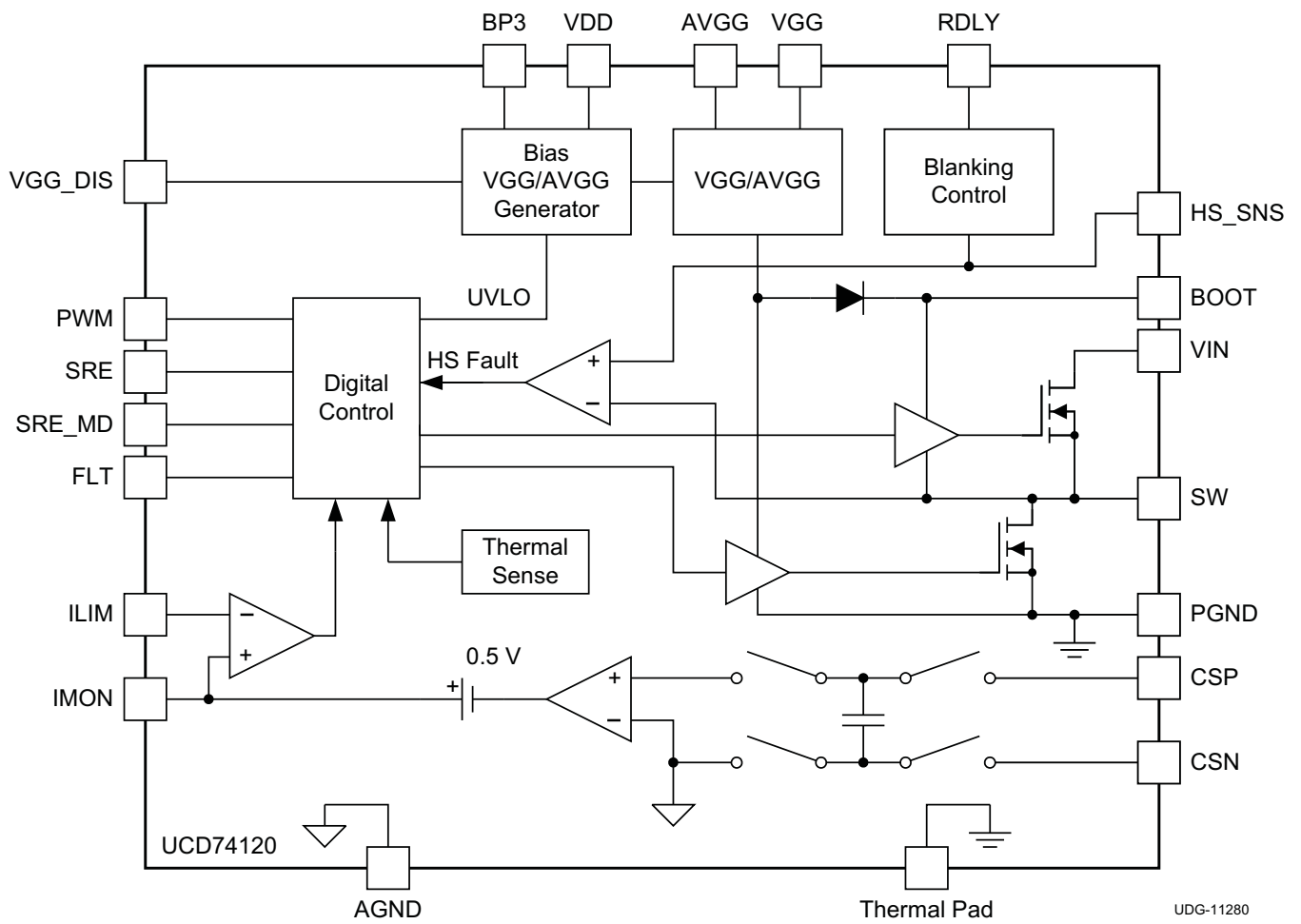
PIN		I/O	DESCRIPTION
NAME	NO.		
N/C	4		Not internally connected.
	6		
	34		
PGND	13		Power ground pins. These pins provide a return path for low-side FET and the low-side gate driver.
	14		
	15		
	16		
	17		
	18		
	19		
	20		
PWM	38	I	PWM input. This pin is a digital input capable of accepting 3.3 V or 5 V logic level signals. A Schmitt trigger input comparator desensitizes this pin from external noise. When SRE mode is high, this pin controls both gate drivers. When SRE mode is low, this pin only controls the high-side driver. This pin can detect when the input drive signal has switched to a high impedance (tri-state) mode. When the high impedance mode is detected, both the high-side gate and low-side gate signals are held low.
RDLY	39	I	Requires a resistor to AGND for setting the current sense blanking time for the high-side current sense comparator and output current limit circuitry.
SRE	31	I	Synchronous rectifier enable or low-side input. This pin is a digital input capable of accepting 3.3V or 5V logic level signals. A Schmitt trigger input comparator desensitizes this pin from external noise. When SRE mode is high, this signal, when low, disables the synchronous rectifier FET. The low-side gate signal is held off. When SRE mode is high, this signal, when high, allows the low-side gate signal to function according to the state of the PWM pin. When SRE mode is low, this pin is a direct input to the low-side gate driver.
SRE_MD	30	I	Synchronous rectifier enable mode select pin. When pulled high to BP3, the high-side and low-side gate drive timing is controlled by the PWM pin. Anti-cross-conduction logic prevents simultaneous application of high-side and low-side gate drive. When pulled low to AGND, independent operation of the high-side and low-side gate is selected. The high-side gate is directly controlled by the PWM signal. The low-side gate is directly controlled by the SRE signal. No anti-cross-conduction circuitry is active in this mode. This pin should not be left floating.
SW	7	I/O	Sense line for the adaptive anti-cross conduction circuitry. Serves as common connection for the flying high side FET driver.
	8		
	9		
	10		
	11		
	12		
VDD	27	I	Input voltage to internal driver circuitry and control circuitry. Connect a low ESR bypass ceramic capacitor of 100 nF or greater from this pin to AGND.
VGG	3	I/O	Gate drive voltage supply. When VGG_DIS is low, VGG is generated by an on-chip linear regulator. Nominal output voltage is 6.4 V. When VGG_DIS is high, an externally supplied gate voltage can be applied to this pin. Connect a 4.7- μ F, low-ESR, ceramic capacitor from this pin to PGND.
VGG_DIS	2	I	VGG disable pin. When pulled high to BP3, the on-chip VGG linear regulator is disabled. When disabled, an externally supplied gate voltage must be connected to the VGG pin. Connect this pin to AGND to use the on-chip regulator.
VIN	21–26	I	Power input to the high-side FET.
Thermal Pad			Power Pad for better thermal performance. It is also connected to PGND internally.

UCD74120

ZHCSAG0 – OCTOBER 2012

www.ti.com.cn

BLOCK DIAGRAM



DETAILED DESCRIPTION

Introduction

The UCD74120, a power stage for synchronous buck converter with current measurement and fault detection capabilities makes it an ideal partner for digital power controllers. This device incorporates two high-current gate drive stages, two high performance NexFET power MOSFETs and sophisticated current measurement circuitry that allows for the monitoring and reporting of output load current. Two separate fault detection blocks protect the power stage from excessive load current or short circuits. On-chip thermal shutdown protects the device in case of severe over-temperature conditions. Detected faults immediately truncate the power conversion cycle in progress, without controller intervention, and assert a digital fault flag (FLT). An on-chip linear regulator supplies the gate drive voltage. If desired, this regulator can be disabled and an external gate drive voltage can be supplied. Mode selection pins allow the device to be used in synchronous mode or independent mode. In synchronous mode, the high-side and low-side gate timing is controlled by a single PWM input. Anti-cross-conduction dead-time intervals are applied automatically to the gate drives. In independent mode, the PWM and SRE pins directly control the high-side and low-side gate drive signals. Independent mode automatically disables dead-time logic. When operating in synchronous mode, the use of the low-side FET can be disabled under the control of the SRE pin. Disabling the low-side FET facilitates start-up into a pre-bias voltage and is can reduce power consumption at light loads in some applications.

PWM Input (PWM)

The PWM input pin accepts the digital signal from the controller that represents the desired high-side FET on-time duration. This PWM input accepts 3.3-V logic levels and 5-V input levels. The SRE mode pin sets the behavior of the PWM pin. When the SRE mode pin is asserted high, the device enters synchronous mode. In synchronous mode, PWM input signal controls the timing of both the high-side gate drive and the low-side gate drive. When PWM is high, the high-side gate drive (HS Gate) is on and the low-side gate drive is off. When PWM is low, the high-side gate drive is off and the low-side gate drive is on. Automatic anti-cross-conduction logic monitors the gate to source voltage of the FETs to verify that the proper FET is turned OFF before the other FET is turned ON. When the SRE mode pin is asserted low, the device enters independent mode. In independent mode, the PWM input controls the high-side gate drive only. When PWM is high, the high-side gate drive is ON. In independent mode, the SRE pin directly controls the low-side FETs. No anti-cross-conduction logic is active in independent mode. The user must ensure that the PWM and SRE signals do not overlap.

PWM input signal can detect when the device has entered a tri-state mode. When tri-state mode is detected, both the high-side and low-side gate drive signals remain OFF. To support this tri-state mode, the PWM input pin has an internal pull-up resistor of approximately 50-k Ω connected to the 3.3 V input. It also has a 50-k Ω pull-down resistor to ground. During normal operation, the PWM input signal swings below 0.8 V and above 2.5 V. If the source driving the PWM pin enters a tri-state or high impedance state, the internal pull-up/pull-down resistors tend to pull the voltage on the PWM pin to 1.65 V. If the voltage on the PWM pin remains within the 0.8 V to 2.5 V tri-state detection range for longer than the tri-state detection hold-off time (t_{HLD_R}), then the device enters tri-state mode and turns both gate drives OFF. This behavior occurs regardless of the state of the SRE mode and SRE pins. When exiting tri-state mode, PWM should first be asserted low. Asserting the PWM pin low ensures that the bootstrap capacitor is recharged before attempting to turn on the high-side FET.

The logic threshold of this pin typically exhibits 900 mV of hysteresis to provide noise immunity and ensure glitch-free operation of the gate drivers.

Synchronous Rectifier Enable Input (SRE)

The SRE (synchronous rectifier enable) pin is a digital input with an internal 10-k Ω pull-up resistor connected to the 3.3-V input. It can accept 3.3-V logic levels and 5-V logic levels. The SRE mode pin sets the behavior of the SRE pin. When the SRE mode pin is asserted high, the device enters synchronous mode. In synchronous mode, the input, when asserted high, enables the operation of the low-side synchronous rectifier FET. The PWM input controls the state of the low-side gate drive signal. When the SRE pin is asserted low while in synchronous mode, the low-side FET gate drive remains low, maintaining the FET OFF. While remaining OFF, current flow in the low-side FET is restricted to its intrinsic body diode. When the SRE mode pin is asserted low, the device is placed in independent mode. In this mode, the state of the low-side gate drive signal follows the state of the SRE signal. It is completely independent of the state of the PWM signal. No anti-cross-conduction logic is active in independent mode. The user must ensure that the PWM and SRE signals do not overlap.

The logic threshold of this pin typically exhibits 450 mV of hysteresis to provide noise immunity and ensure glitch-free operation of the low-side gate driver.

SRE Mode (SRE_MD)

The SRE mode pin is a digital input that accepts 3.3-V logic levels and levels up to 5-V. This pin establishes the operational mode on the device. When asserted high, the device enters synchronous mode. In synchronous mode, the PWM input controls the behavior of both the high-side and low-side gate drive signals. When asserted low, this pin configures the device for independent mode. In independent mode, the PWM pin controls the high-side FET and the SRE pin controls the low-side FET. The SRE mode pin should be tied permanently high or low depending on the power architecture being implemented. It should not be switched dynamically while the device is in operation. This pin can be tied to the BP3 pin to permanently operate in synchronous mode.

Input Voltage for Internal Circuits (VDD)

The VDD pin supplies power to the internal circuits of the device. An internal linear regulator that provides the V_{VGG} gate drive voltage conditions the input power. A second regulator that operates off of the V_{VGG} rail produces an internal 3.3-V supply that powers the internal analog and digital functional blocks. The BP3 pin provides access for a high frequency bypass capacitor on this internal rail. The VGG regulator produces a nominal output of 6.4 V. The undervoltage lockout (UVLO) circuitry monitors the output of the VGG regulator. The device does not attempt to produce gate drive pulses until the VGG voltage is above the UVLO threshold. This delay ensures that there is sufficient voltage available to drive the power FETs into saturation when switching activity begins.

Voltage Supply for Gate Drive and Internal Control Circuitry (VGG and AVGG)

The VGG pin is the gate drive voltage for the high-current gate drive stages. The AVGG pin is the voltage supply to internal control circuitry. The on-chip regulator can supply the voltage internally on the VGG pin, or the user can supply the voltage externally. When using the internal regulator, the VGG_DIS pin should be tied low. When using an external source for VGG, the VGG_DIS pin must be tied high. The device draws current from the VGG supply in fast, high-current pulses. Connect a 4.7- μ F ceramic capacitor between the VGG pin and the PGND pin as close as possible to the package.

Connect a resistor with a value between 1 Ω and 2 Ω between the AVGG pin and the VGG pin. Connect a low-ESR bypass ceramic capacitor of 100 nF or greater between the AVGG pin and AGND.

Whether the voltage is internally or externally supplied, UVLO circuitry monitors the voltage on the VGG pin. The voltage must be higher than the UVLO threshold before power conversion can occur. Note that the FLT pin is asserted high when V_{VGG} is below the UVLO threshold.

VGG Disable (VGG_DIS)

The VGG_DIS pin, when asserted high, disables the on-chip VGG linear regulator. When tied low, the VGG linear regulator derives the VGG supply from V_{IN} . Permanently tie the VGG_DIS pin high or low depending on the power architecture being implemented. The VGG_DIS pin should not be switched dynamically while the device is in operation.

Switching Node (SW)

The SW pin connects to the switching node of the power conversion stage. It acts as the return path for the high-side gate driver. When configured as a synchronous buck stage, the voltage swing on SW normally traverses from below ground to well above V_{IN} . Parasitic inductance in the high-side FET and the output capacitance (C_{OSS}) of both power FETs form a resonant circuit that can produce high frequency (> 100 MHz) ringing on this node. The voltage peak of this ringing, if not controlled, can be significantly higher than V_{IN} . Ensure that no peak ringing amplitude exceeds the absolute maximum rating limit for the pin.

In many cases, connecting a series resistor and capacitor snubber network from the switching node to PGND can dampen the ringing and decrease the peak amplitude. Make allowances for snubber network components during the layout of the printed circuit board. If testing reveals that the ringing amplitude at the SW pin exceeds the limit, then populate the snubber components.

Placing a BOOT resistor with a value between $5\ \Omega$ and $10\ \Omega$ in series with the BOOT capacitor slows down the turn-on of the high-side FET and can help to reduce the peak ringing at the switching node as well.

Bootstrap (BST)

The BST pin provides the drive voltage for the high-side FET. A bootstrap capacitor connects this pin to the SW node. Internally, a diode connects the BST pin to the VGG supply. In normal operation, when the high-side FET is off and the low-side FET is on, the SW node pulls to ground and, thus, maintains one side of the bootstrap capacitor at ground potential. The internal diode connected to VGG clamps the other side of the bootstrap capacitor. The voltage across the bootstrap capacitor at this point is the magnitude of the gate drive voltage available to switch-on the high-side FET. The bootstrap capacitor should be a low-ESR ceramic type, with a recommended minimum value of $0.22\ \mu\text{F}$. The recommended minimum voltage rating is 16 V or higher.

Current Sense (CSP, CSN)

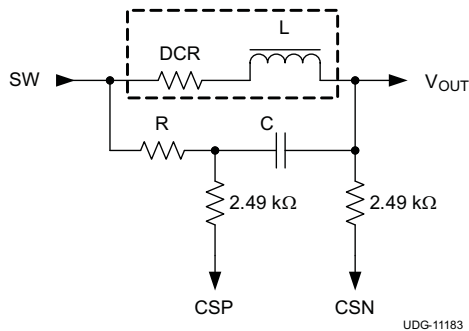
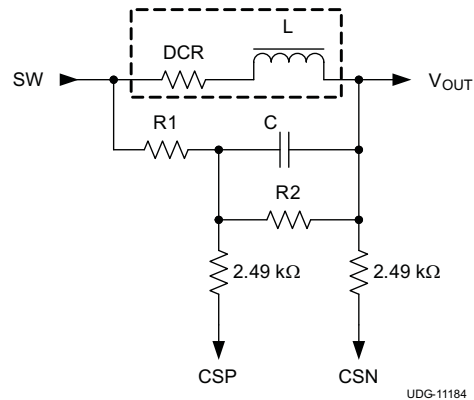
The CSP and CSN pins are the input to the differential current sense amplifier. The current sense positive (CSP) pin connects to the non-inverting input, the current sense negative (CSN) connects to the inverting input. This amplifier allows the device to monitor and measure the output current of the power stage. The circuitry can be used with a discrete, low value, series current sense resistor, or can make use of the popular inductor DCR sense method.

Figure 1 illustrates the DCR method of current sensing, showing a series resistor and capacitor network added across the buck stage power inductor. When the value of L/DCR is equal to RC , then the *voltage* developed across the capacitor, C , is a replica of the voltage waveform the *ideal current* would induce in the dc resistance (DCR) of the inductor. This method does *not* detect changes in current due to changes in inductance value caused by saturation effects. The value used for C should be between $0.1\ \mu\text{F}$ and $2.2\ \mu\text{F}$. This maintains low impedance of the sense network, which reduces its susceptibility to noise pickup from the switching node. The trace lengths of the CSP and CSN signals should be kept short and parallel. To aid in rejection of high frequency common-mode noise, a series $2.49\text{-k}\Omega$ resistor should be added to both the CSP and CSN signal paths, with the resistors being placed close to the pins at the package. This small amount of additional resistance slightly lowers the current sense gain.

Select power inductors with the lowest possible DCR in order to minimize losses. Typical DCR values range between $0.5\ \text{m}\Omega$ and $5\ \text{m}\Omega$. With a load current of 25 A, the voltage presented across the CSP and CSN pins ranges between 12.5 mV and 125 mV. Note that this small differential signal is superimposed on a large common mode signal that is the dc output voltage, which makes the current sense signal challenging to process.

The UCD74120 uses switched capacitor technology to perform the differential to single-ended conversion of the sensed current signal. This technique offers excellent common mode rejection. The differential CSP-CSN signal is amplified by a factor of 47 and then a fixed 500-mV pedestal voltage is added to the result. The IMON pin senses this signal.

When using inductors with DCR values of $1.5\ \text{m}\Omega$ or higher, it may be necessary to attenuate the input signal to prevent saturation of the current sense amplifier. Add of resistor R_2 as shown in **Figure 2** to provide attenuation.


Figure 1. DCR Current Sense

Figure 2. Attenuating the DCR Sense Signal

The amount of attenuation is equal to $R2/(R1 + R2)$. The equivalent resistance value to use in the $L/DCR = RC$ formula is the parallel combination of $R1$ and $R2$. Thus, when using the circuit shown in [Figure 2](#),

$$\frac{L}{DCR} = \frac{C \times R1 \times R2}{(R1 + R2)} \quad (1)$$

Current Monitor (IMON)

The IMON pin signal is a voltage proportional to the output current delivered by the power stage. [Equation 2](#) describes the voltage magnitude when using the circuit shown in [Figure 1](#) and reflects the gain reduction caused by the series 2.49-kΩ resistors.

$$V(I_{OUT}) = 0.5 + 47 \times DCR \times I_{LOAD} \quad (2)$$

If the calculated value of V_{IMON} at maximum load exceeds 2.5 V, then the circuit of [Figure 2](#) should be used. When using the circuit shown in [Figure 2](#), the modified [Equation 3](#) describes the voltage on IMON.

$$V(I_{OUT}) = 0.5 + 47 \times DCR \times I_{LOAD} \times \left(\frac{R2}{R1 + R2} \right) \quad (3)$$

In either case, the output voltage is 500 mV at no load. Current that is sourced to the load causes the IMON voltage to rise above 500 mV. Current that is forced into the power stage (sinking current) is considered *negative* current and causes the IMON voltage to fall below 500 mV. The usable dynamic range of the IMON signal is approximately 100 mV to 3.1 V. Note that this signal swing could exceed not only the maximum range of an analog to digital converter (ADC) that may be used to read or monitor the IMON signal, but also the maximum programmable limit for the fault OC threshold. For example, the UCD92xx family of digital controllers has maximum limit of 2.5 V for the ADC converter and 2.0 V for the fault overcurrent threshold, even though the input pin can tolerate voltages up to 3.3 V.

The device internally feeds the IMON voltage (V_{IMON}) to the non-inverting input of the output overcurrent fault comparator. Set the overcurrent threshold to approximately 150% of the rated power stage output current plus one half of the peak-to-peak inductor ripple current. This setting requires that the IMON signal remain within its linear dynamic range at this threshold load current level. This requirement may force the use of the attenuation circuit of [Figure 2](#). Note that the IMON voltage (that goes to the output overcurrent fault comparator) is held during the blanking interval set by the resistor on the RDLY pin. This means that the IMON pin does not reflect output current changes during the blanking interval, and that a fault is not flagged until the blanking interval terminates.

Current Limit (ILIM)

The ILIM pin feeds the inverting input of the output overcurrent fault comparator. The voltage applied to this pin sets the overcurrent fault threshold. When the voltage on the I_{MON} pin exceeds the voltage on this pin, the device flags a fault. The voltage on this pin can be set by a voltage divider, a DAC, or by a filtered PWM output. The usable voltage range of the ILIM pin is approximately 0.6V to 3.1V. This represents the linear range of the IMON signal for sourced output current. When using a voltage divider to set the threshold, add a small (0.01-μF) capacitor to BP3 to improve noise immunity.

Blanking Time (RDLY)

The RDLY pin sets the blanking time of the high-side fault detection comparator. A resistor to AGND sets the blanking time according to the following formula, where t_{BLANK} is in nanoseconds and RDLY is in k Ω . Do not use a value greater than 25 k Ω for the RDLY resistor.

$$R_{\text{RDLY}} = \frac{(t_{\text{BLANK}} - 54.4)}{8.76} \quad (4)$$

To calculate the nominal blanking time for a given value of resistance, use [Equation 5](#).

$$t_{\text{BLANK}} = 8.76 \times R_{\text{RDLY}} + 54.4 \quad (5)$$

The blanking interval begins on the rising edge of SW. During the blanking time the high-side fault comparator remains OFF. A high-side fault flags when the voltage drop across the high-side FET exceeds the threshold set by the HS_SNS pin. Blanking is required because the high amplitude ringing that occurs on the rising edge of SW would otherwise cause false triggering of the fault comparator. The required amount of blanking time is a function of the high-side FET, the PCB layout, and whether or not a snubber network is being used. A value of 100 ns is a typical starting point. An R_{RDLY} of 8.06 k Ω provides 125 ns of blanking. Maintains a blanking interval as short as possible, consistent with reliable fault detection. The blanking interval sets the minimum duty cycle pulse width where high-side fault detection is possible. When the duty-cycle of the PWM pulses are narrower than the blanking time, the high-side fault detection comparator is held off for the entire on-time and is, therefore, blind to any high-side faults.

Internally, a 90- μA current source supplies the RDLY. When using the default value of 8.06 k Ω , the voltage measured on the RDLY pin is approximately 725 mV.

Fault Flag (FLT)

The digital output fault flag (FLT) pin asserts when the device detects a significant fault. It alerts the host controller to an event that interrupts power conversion. The device holds the FLT pin low during normal operation.

When a fault is detected, the FLT pin asserts high (3.3 V). There are four events that can trigger the FLT signal:

- output overcurrent
- high-side overcurrent
- undervoltage lockout (UVLO)
- thermal shutdown

The [Fault Behavior](#) section describes the operation of the device during fault conditions. When asserted in response to an overcurrent fault, the FLT signal resets to low at the falling edge of a subsequent PWM pulse, provided no faults are detected during the on-time of the pulse. If the fault is still present, the flag remains asserted. When asserted in response to an UVLO or thermal shutdown event, the FLT pin automatically de-asserts when the UVLO or thermal event has passed. If the on-time of the PWM pulse is less than 100 ns, then more than one pulse may be required to reset the flag.

3.3-V BP Regulator (BP3)

The BP3 pin provides a connection point for a bypass capacitor that quiets the internal 3.3-V voltage rail. Connect a 1- μF (or greater) ceramic capacitor from this pin to analog ground. Do not draw current from this pin. The BP3 pin is not intended to be a significant source of 3.3-V input voltage. However, the user can design an application that includes 3.3-V source for an ILIM voltage divider and a tie point for the SRE mode pin. Limit the current drawn 100 μA or less.

Fault Behavior

When faults are detected, the device reacts immediately to minimize power dissipation in the FETs and protect the system. The type of fault influences the behavior of the gate drive signals.

Immediately after a thermal shutdown fault occurs, the device forces both high-side gate and low-side gate low. They remain low (regardless of the state of the PWM and the SRE pin) for the duration of the thermal shutdown.

A UVLO fault occurs when the voltage on the VGG pin is less than the UVLO threshold. During this time, the device drives both the high-side gate and low-side gate to low, regardless of the state of the PWM the and SRE pins. The fault automatically clears when V_{VGG} rises above the UVLO threshold.

When the device detects either a high-side fault or an output overcurrent fault, the FLT pin asserts high, and the device immediately pulls both gate signals to low. During a high-side fault, the device issues a high-side gate pulse with each incoming PWM pulse. If the fault is still present, the high-side gate signal again truncates. This behavior repeats on a cycle-by-cycle basis until the fault clears or the PWM input remains low. [Figure 3](#) illustrates this behavior

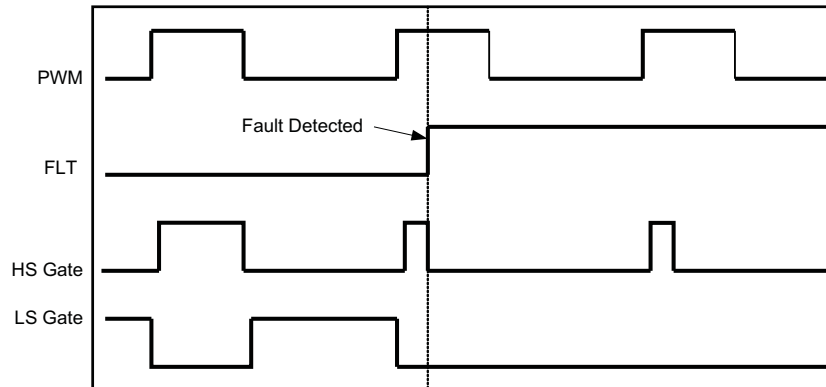


Figure 3. High-side Overcurrent Fault Response

When the device detects a high-side fault and output overcurrent fault concurrently, then it immediately turns OFF and holds OFF both FET drives. If the output overcurrent fault remains present at the next PWM rising edge, then the device issues no high-side gate pulse continue to be hold both gates OFF. Unlike the high-side fault detection circuitry, the output overcurrent fault circuitry does not reset on a cycle-by-cycle basis. The output current must fall below the overcurrent threshold before switching resumes.

FLT Reset

With the exception of a UVLO fault or a thermal shutdown fault, subsequent PWM pulses clears the FLT flag, after it is asserted. The device clears the FLT flag at the falling edge of the next PWM pulse, provided a fault condition is not asserted during the entire on-time of the PWM pulse. If the device detects a fault during the on-time interval, the FLT pin remains asserted. [Figure 4](#) illustrates this behavior.

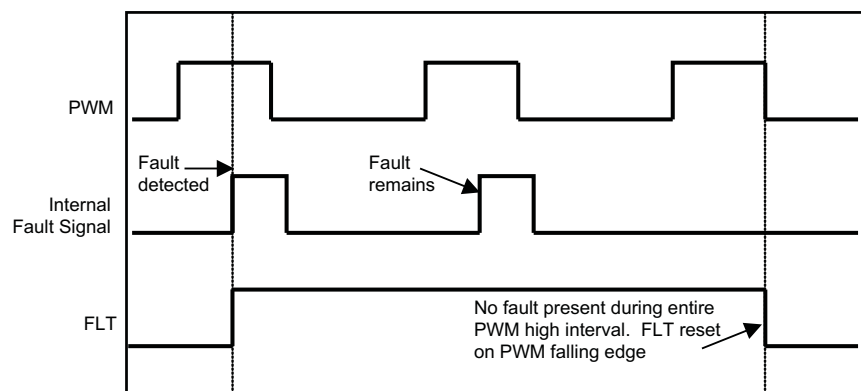




Figure 4. FLT Reset Sequence

Whenever the voltage on the VGG pin is below the UVLO falling threshold (as at the time of initial power-up for example) the FLT pin asserts. When the voltage on the VGG pin rises above the UVLO rising threshold, the device clears the FLT automatically. This feature permits the FLT pin to be used as a *power not good* signal at initial power-up to signify that there is insufficient gate drive voltage available to permit proper power conversion. When FLT goes low, it is an indication of *gate drive power good* and power conversion can commence. After initial power-up, the assertion of the FLT flag indicates that power conversion has stopped or has been limited by a fault condition.

Thermal Shutdown

If the junction temperature exceeds approximately 165°C, the device enters thermal shutdown. The device asserts the FLT pin and turns OFF both gate drivers. When the junction temperature cools by approximately 20°C, the device exits thermal shutdown. The FLT flag resets immediately after exiting thermal shutdown.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UCD74120RVFR	ACTIVE	LQFN-CLIP	RVF	40	3000	RoHS-Exempt & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	UCD74120	
UCD74120RVFT	ACTIVE	LQFN-CLIP	RVF	40	250	RoHS-Exempt & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	UCD74120	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

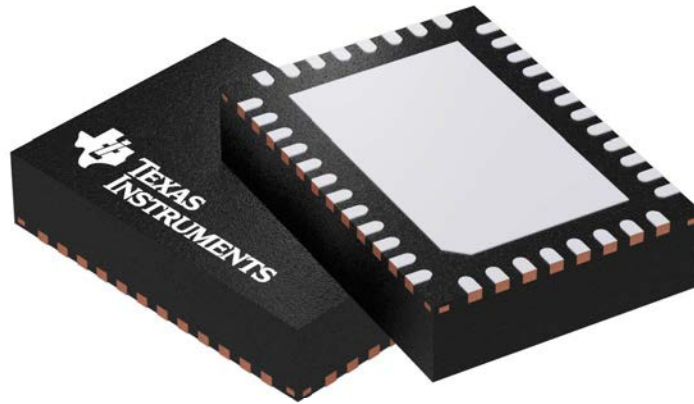
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

GENERIC PACKAGE VIEW

RVF 40

LQFN-CLIP - 1.52 mm max height

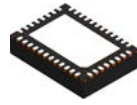
PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4211383/D

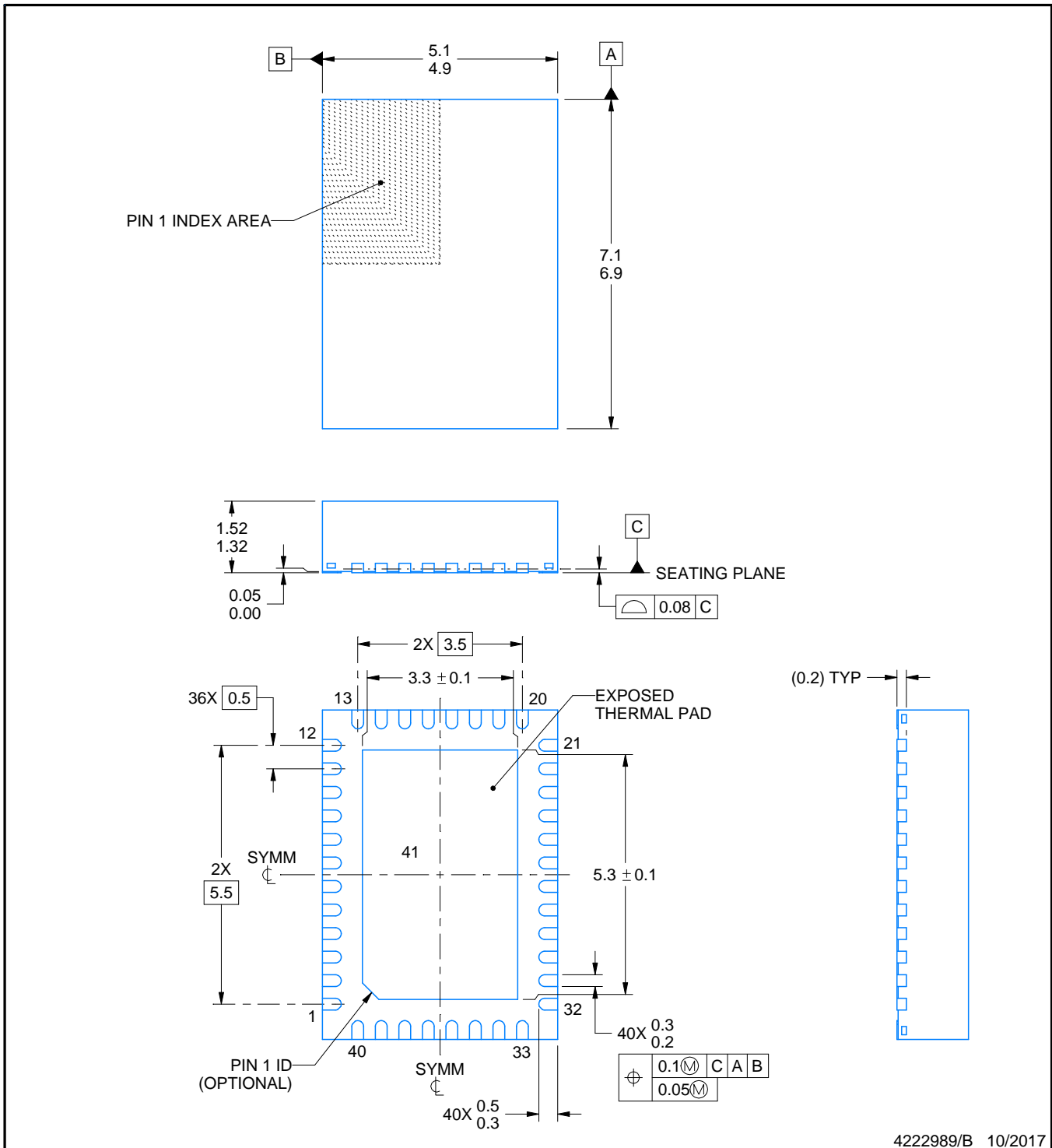
RVF0040A



PACKAGE OUTLINE

LQFN-CLIP - 1.52 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4222989/B 10/2017

NOTES:

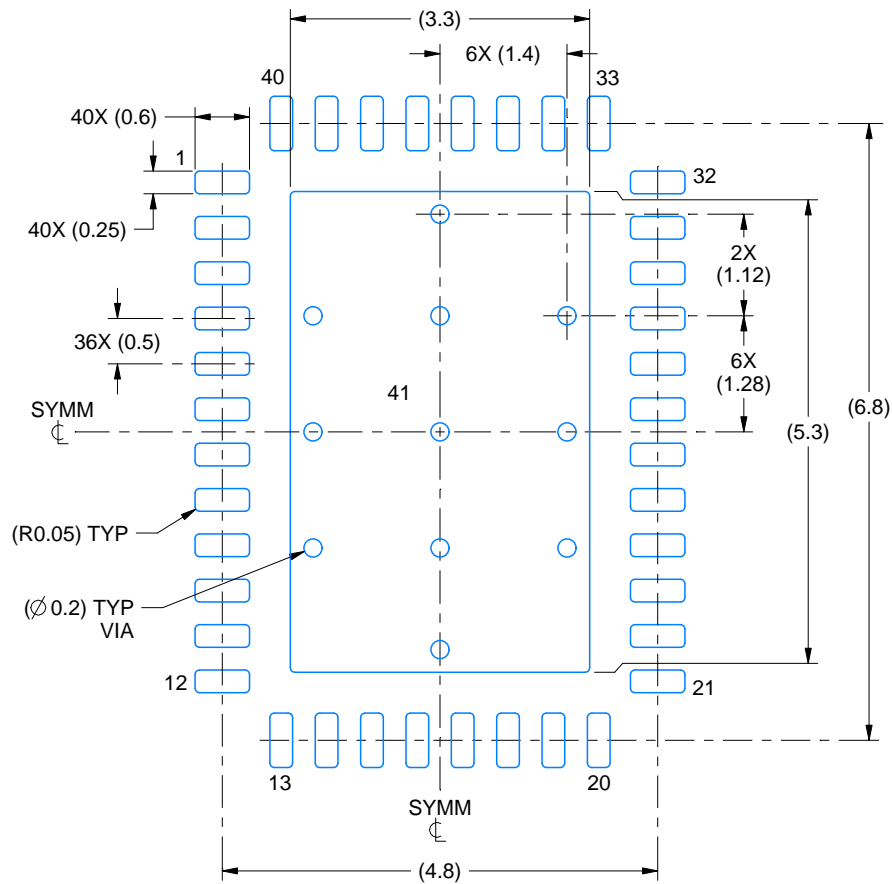
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. Reference JEDEC registration MO-220.

EXAMPLE BOARD LAYOUT

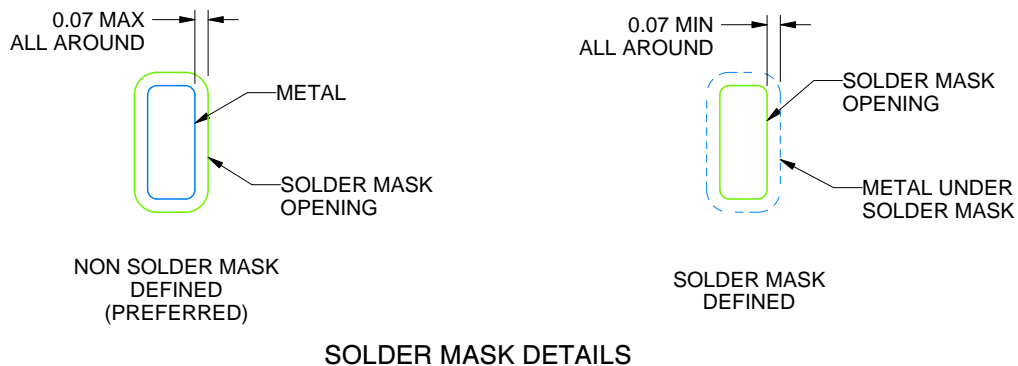
RVF0040A

LQFN-CLIP - 1.52 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
SCALE:12X



SOLDER MASK DETAILS

4222989/B 10/2017

NOTES: (continued)

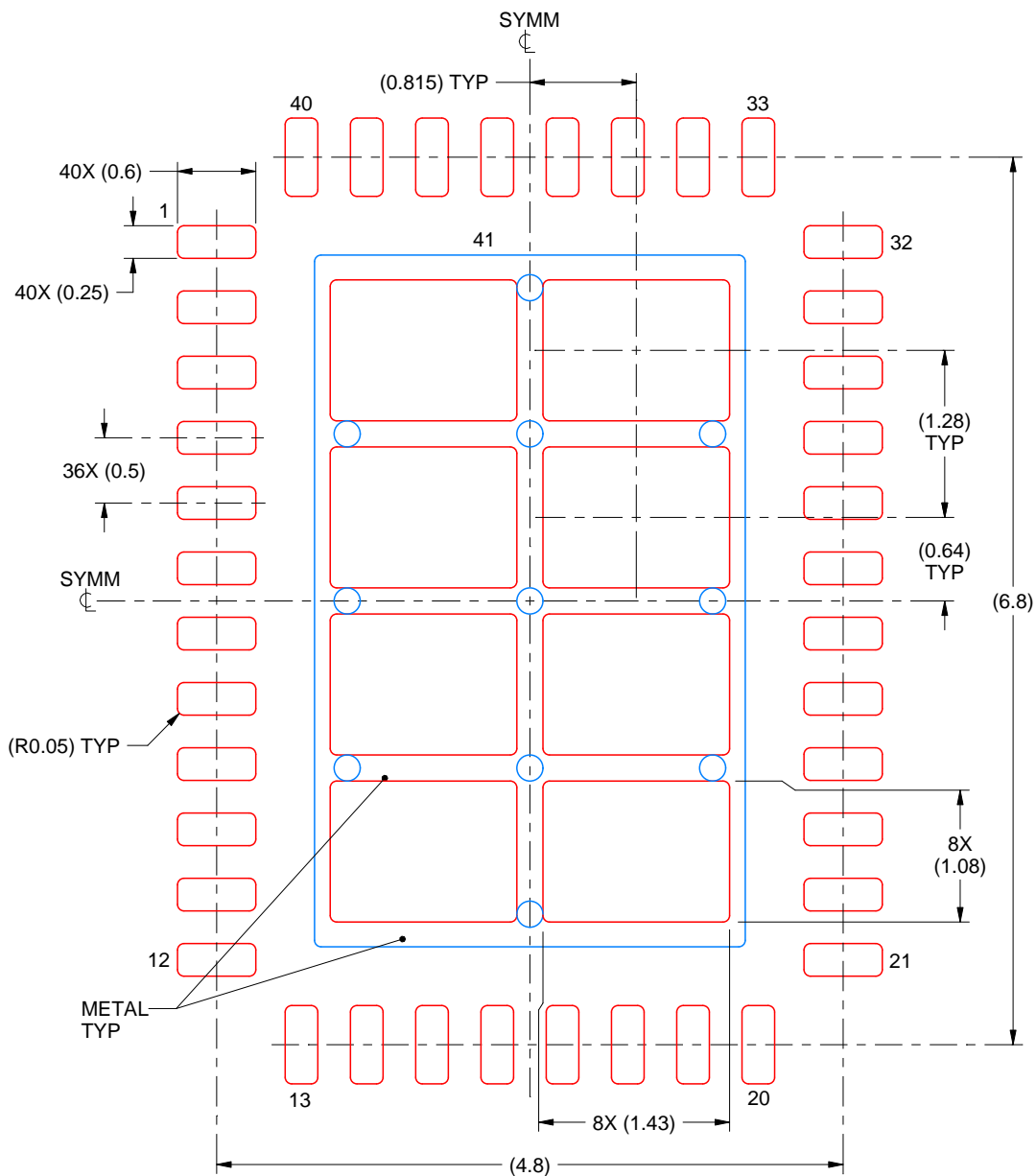
5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

RVF0040A

LQFN-CLIP - 1.52 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
71% PRINTED SOLDER COVERAGE BY AREA
SCALE:18X

4222989/B 10/2017

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

重要声明和免责声明

TI 均以“原样”提供技术性 & 可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证其中不含任何瑕疵，且不做任何明示或暗示的担保，包括但不限于对适销性、适合某特定用途或不侵犯任何第三方知识产权的暗示担保。

所述资源可供专业开发人员应用 TI 产品进行设计使用。您将对以下行为独自承担全部责任：(1) 针对您的应用选择合适的 TI 产品；(2) 设计、验证并测试您的应用；(3) 确保您的应用满足相应标准以及任何其他安全、安保或其他要求。所述资源如有变更，恕不另行通知。TI 对您使用所述资源的授权仅限于开发资源所涉及 TI 产品的相关应用。除此之外不得复制或展示所述资源，也不提供其它 TI 或任何第三方的知识产权授权许可。如因使用所述资源而产生任何索赔、赔偿、成本、损失及债务等，TI 对此概不负责，并且您须赔偿由此对 TI 及其代表造成的损害。

TI 所提供产品均受 TI 的销售条款 (<http://www.ti.com.cn/zh-cn/legal/termsofsale.html>) 以及 [ti.com.cn](http://www.ti.com.cn) 上或随附 TI 产品提供的其他可适用条款的约束。TI 提供所述资源并不扩展或以其他方式更改 TI 针对 TI 产品所发布的可适用的担保范围或担保免责声明。

邮寄地址：上海市浦东新区世纪大道 1568 号中建大厦 32 楼，邮政编码：200122

Copyright © 2020 德州仪器半导体技术（上海）有限公司